Monday, June 19, 2023, afternoon

1st Tutorial



Bernhard Kneer / Carl Zeiss SMT GmbH, Oberkochen (Germany)
Head of Product Systems Engineering
"Technology of EUV Lithography Optics"

2nd Tutorial



Takeo Watanabe / University of Hyogo, Hyogo (Japan)
Director of Center for EUVL (CEL) at Laboratory of Advanced Science and Technology for Industry (LASTI), and Executive Advisor to the President, University of Hyogo

"The Dawn of EUV Lithography Technology, and its Current Status and Future Prospect"

1st Keynote



Tuesday, June 20, 2023, morning

Giacomo Indiveri / University of Zurich and ETH Zurich (Switzerland)
Professor of Neuromorphic Cognitive Systems
"Neuromorphic Intelligence: mixed-signal spiking neural networks
for on-line sensory processing at the edge"

2nd Keynote



Joe English / INTEL Corporation, Leixlip (Ireland)
Fab 34 Factory Manager / Technology transfer and ramp of Intel 4
"Photomask technology as a key enabler of EUV in high volume manufacturing"

Tuesday, June 20, 2023, morning

3rd Keynote



Jo Finders / ASML, Veldhoven (The Netherlands)
ASML Fellow and SPIE Fellow
Manager of the EUV imaging and focus group within system engineering at ASML 2023
"Taking lithography to the max"

Invited Presentation, Wednesday, June 21, morning

PMJ 2023 Best Poster

Hiroshi Nakata / Dai Nippon Printing, Saitama (Japan)

Manager of Digital Transformation Promotion Department,

Photomask Division

"A Study of Photomask Manufacture Process based on AI Technology"

Wednesday, June 21, 2023, morning

4th Keynote



Christian Koitzsch / BOSCH, Dresden (Germany)
Managing Director Robert Bosch Semiconductor Manufacturing
Dresden GmbH

"Bosch Dresden – from Greenfield to High Yield"

5th Keynote



Dominik Thron / INFINEON, Dresden (Germany)
Vice President Frontend Production at Infineon Technologies
Dresden

"Infineon Dresden's growth to a European Manufacturing and Development Hub"



Invited Presentations, Tuesday, June 20, morning

Björn Butscher / Carl Zeiss SMT GmbH, Oberkochen (Germany) Product Systems Engineer Projection "Emergence of next generation EUV optics: status, outlook and future"



Andreas Erdmann / Fraunhofer IISB and University of Erlangen (Germany)
Head of Computational Lithography and Optics Group / SPIE Fellow
"Exploration of imaging solutions for high NA EUV lithography by combination of dual monopole exposure strategies with low n absorbers"



Invited Presentations, Tuesday, June 20, afternoon

Sang-Hee Lee / Samsung Electronics, Hwaseong (Korea)
Corporate Vice President and Head of Mask Development Team
"The History of E-beam Mask Writing and Innovations for EUV Mask Patterning"



Shingo Yoshikawa / Dai Nippon Printing, Saitama (Japan)
Technical Director of Dai Nippon Printing Co., Ltd Photomask Division
"State-of-the-art EUV mask process development by the combination of MBMW and ultra-high resolution CAR"



Invited Poster Presentation, Tuesday, June 20, afternoon

Sven Glabisch / RWTH Aachen (Germany)
PhD student at the chair for Technology of Optical Systems
"Investigation of stochastic roughness effects for nanoscale grating characterization with a stand-alone EUV spectrometer"



Invited Presentation, Wednesday, June 21, morning

Ksenija Varga / EV Group, St. Florian am Inn (Austria) Business Development Manager

"LITHOSCALE® Features Accomplish Dual Exposure and High Resolution Patterning"

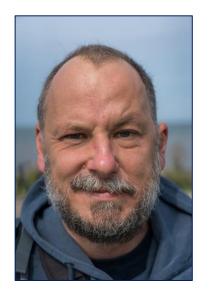


Invited Presentations, Wednesday, June 21, afternoon

Avi Cohen / Carl Zeiss SMT, Bar Lev Industrial Park, Misgav (Israel)
Application Manager, Tuning Field of Business
"Leading Control of Wafer Overlay and CDU Residuals Beyond the Available DUV and/or EUV Lithography Knobs"



Yannick Hermans / IMEC, Leuven (Belgium)
Research Engineer in the lithography development team of imec
"EUV Mask Defect Inspection for the 3nm Technology Node"



Invited Presentation, Wednesday, June 21, afternoon

Martin Sczyrba / AMTC, Dresden (Germany)
Senior Member of Technical Staff in Product Technology
"Manufacturing of NIL Masters for AR/VR Applications and Metalenses using Photomask Technology"





Florent Dettoni - Metrology Advanced Solutions Technical Leader and

Bertrand Le Gratiet - Technical Staff Fellow Lithography / Metrology / **STMicroelectronics**, Crolles (France)

"The image lab sandbox, pulling image computing in wafer fab metrology environment"